

TN00006

LPC1800 and LPC4300 MxMEMMAP memory map

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Technical note

Document information

Info	Content
Keywords	LPC1800, LPC4300, MxMEMMAP, memory map
Abstract	This technical note describes available boot addresses for the LPC1800 and LPC4300 memory map registers



Revision history

Rev	Date	Description
1	20121130	Initial version.

Contact information

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1. Introduction

The LPC1800 and LPC4300 MCUs both contain one or more registers called MxMEMMAP. These registers can be used to modify the MCU's memory map. They affect the instructions fetched when executing code and the local data read and written to by the instructions.

Name	Access	Address offset	Description	Reset value	Reset value after EMC, UART0/3 boot	Reset value after USB0/1 boot	Reference
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For LPC1800 family:

M3MEMMAP	R/W	0x100	ARM Cortex-M3 memory mapping	0x1040000	0x1000000	0x1000000	Table 37
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For LPC4300 family:

M4MEMMAP	R/W	0x100	ARM Cortex-M4 memory mapping	0x1040000	0x1000000	0x1000000	Table 44
M0APPMEMMAP	R/W	0x404	ARM Cortex-M0 memory mapping	0x2000000	<tb>	<tb>	Table 54

The MxMEMMAP registers all have the same layout:

Table 54. Memory mapping register (M0APPMEMMAP, address 0x4004 3404) bit description

Bit	Symbol	Description	Reset value	Access
11:0		Reserved	0	-
31:12	M0APPMAP	Shadow address when accessing memory at address 0x0000 0000	0x2000000	R/W

The lower 12 bits are reserved and must be zero. The field consisting of the remaining bits 31:12 contains the high 20 bits of the address that will be shadowed into address 0. A simpler way to think of this is that the MxMEMMAP register contains an address, which must end in 0x000. Up to 256 MB of the information mapped at the specified memory region, will also appear at 0x00000000. This is called "shadowing" since the information appears both at its original address and at address 0x00000000.

[Fig 1](#) contains an example of how this works on the LPC1850 when booting from external flash memory via the External Memory Controller (EMC).

M3MEMMAP = 0x1C00 0000

This chart shows how the boot ROM initializes M3MEMMAP when booting from external flash. By setting M3MEMMAP to 0x1C00 0000, external static memory chip select CS0 is remapped to the shadow area at 0x0000 0000. Despite the shadow area being 256 MB in size, the internal AHB SRAM located starting at 0x2000 0000 will not be shadowed.*

*The MEMMAP registers only affect the Instruction (I) and Data (D) buses on the M3/M4 cores, so memory with an address > 0x2000 0000 (on the Cortex System Bus) is not able to be shadowed unless it can be accessed by the System (S) bus.

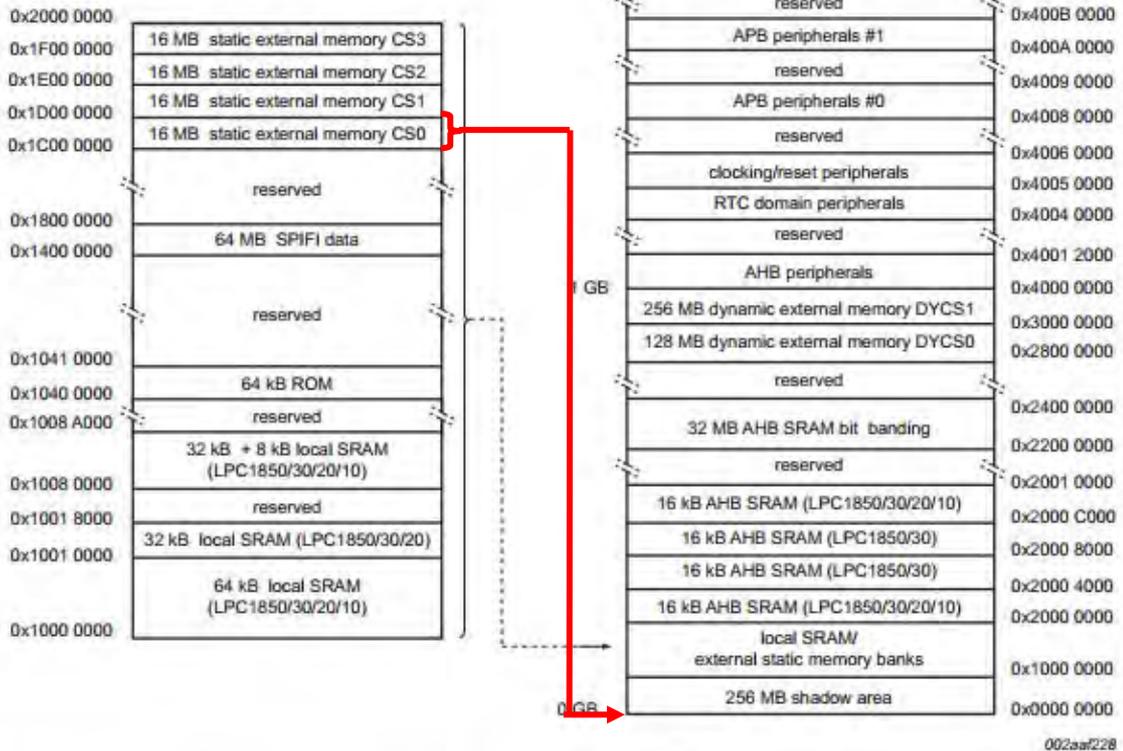


Fig 3. System memory map - flashless parts LPC1850/30/20/10 (see Figure 4 for detailed addresses of all peripherals)

Fig 1. Example of shadowing

1.1 MxMEMMAP FAQ

Q: What address should I build my code for?

A: The intention in providing the MxMEMMAP registers is to make it possible to build for a fixed address. Always building code for 0x0000 0000 could simplify booting from different memories since the code will be the same regardless of the address of the memory. Depending on your tool, it may be difficult to build for 0x0000 0000 because this could break the flash programming algorithms if the tool does not support relocating the code from linker address 0x0000 0000 to the flash memory area during programming.

Q: What if instead of linking for 0x0000 0000, I link my code for another address such as 0x1400 0000, which is SPIFI's lower memory region? Will the code still run?

A: Yes it will. When you build an image for the Cortex-Mx platforms, the first word in the image will be the stack location, and the second word will contain the address of the code's entry point. After mapping your code to 0x0000 0000, the ROM driver reads address 0x0000 0004 to get the code entry point. It then jumps to this address to start your program. If you build for 0x1400 0000, then the code entry point at 0x1400 0004 will be 0x14xx xxxx. This word is remapped to 0x0000 0004 and loaded by the boot ROM resulting in starting your code at 0x14xx xxxx. In this case, the shadow area would only be used by the boot ROM to read the stack pointer and start address, and would be ignored thereafter.

Q: What if I want to use many memories all containing different segments of code?

A: In this case, the shadow area can only represent one memory area and should be set up to point to your boot memory. Code for other memory areas such as DYCS0 (SDRAM) should be linked to the actual memory address, and not linked for 0x0000 0000.

Q: Is the ARM Cortex-M3/M4 VTOR register supported?

A: Yes. VTOR is supported and can be used to move the vector table out of the shadow region and locate it in another memory region. Upon boot, VTOR will be set to 0x0000 0000.

Q: Can on-board bus mastering peripherals such as USB, Ethernet, and DMA access the shadow region?

A: No. The MxMEMMAP mechanism only affects memories as seen by the Cortex-M3/M4 core's I and D or S buses or by the M0 core.

Q: What if I want to use a QSPI memory larger than 64 MB? Can I locate my code at 0 and map the upper SPIFI aperture at 0x8000 0000 to 0 using MxMEMMAP?

A: Yes. Since the SPIFI peripheral can be accessed by the System Bus (S), it will remap to 0x00000000. Other memories at address ranges > 0x20000000 that cannot be accessed by the System Bus (S) will not remap to 0x00000000.

1.2 LPC4300-specific FAQ

On the LPC4300, there are two MxMAP registers. M4MEMMAP controls the memory map for the Cortex-M4, and M0APPMEMMAP controls the memory map for the Cortex-M0. This means that the M0 and M4 can have different memory mapped into the shadow area. This means the code for both cores can be linked to 0x0000 0000 and stored in different memory areas.

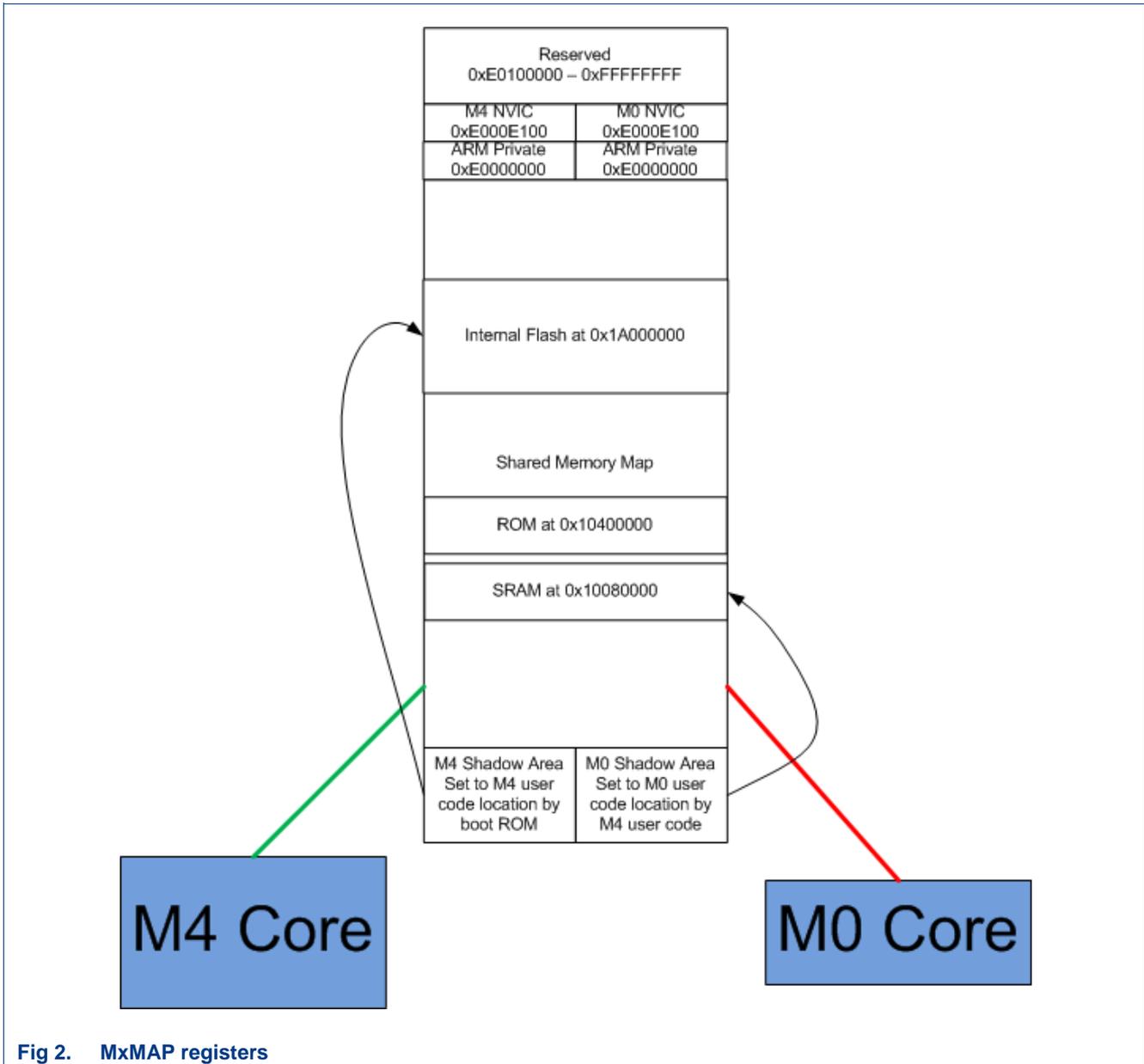


Fig 2. MxMAP registers

Q: How can the M0 and the M4 execute different code at the same address?

A: The MxMEMMAP registers only affect a single core in the MCU. The M4MEMMAP register does not affect the M0 or any peripherals. Neither does the M0MEMMAP register affect the M4 or any peripherals.

Q: Do I have to use M0APPMEMMAP when using the M0 core?

A: You must use M0APPMEMMAP. This is because when the M0 core is let out of reset, it will begin executing at 0x0000 0000. M0APPMEMMAP must be set up so that the M0 can fetch the correct stack pointer and code start address.

Q: Why isn't the VTOR register used?

A: There is a VTOR register on the M3 and M4 cores, but not on the M0 core. Since no VTOR is present on the Cortex-M0 core, the MxMEMMAP register was conceived as a way to remap memory on any Cortex-Mx core.

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